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SEK 18 male low profile solder and press-in RoHS compliant				Recommended configuration of plated through holes for press-in termination In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties – such as mechanical strength and coefficient of friction – we recommend the following configuration of PCB through holes. <table><tr><td rowspan="3">Tin plated PCB (HAL) acc. to EN 60352-5</td><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>Sn</td><td>max. 15 µm</td></tr><tr><td rowspan="3">Chemical tin plated PCB</td><td>plated hole Ø</td><td>0,94 – 1,09 mm</td></tr><tr><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td rowspan="5">Gold /Nickel plated PCB</td><td>Sn</td><td>min. 0,8µm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr><tr><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>Ni</td><td>3 – 7 µm</td></tr><tr><td rowspan="3">Silver plated PCB</td><td>Au</td><td>0,05 – 0,12 µm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr><tr><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td rowspan="3">Copper plated PCB (OSP)</td><td>Cu</td><td>min. 25 µm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr></table>				Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Sn	max. 15 µm	Chemical tin plated PCB	plated hole Ø	0,94 – 1,09 mm	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Gold /Nickel plated PCB	Sn	min. 0,8µm	plated hole Ø	1,00 – 1,10 mm	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Ni	3 – 7 µm	Silver plated PCB	Au	0,05 – 0,12 µm	plated hole Ø	1,00 – 1,10 mm	Drilled hole Ø	1,15-0,03 mm	Copper plated PCB (OSP)	Cu	min. 25 µm	plated hole Ø	1,00 – 1,10 mm	A																																																							
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SEK 18 male low profile solder and press-in



General information

Design	IEC 60603-13
No. of contacts	6,10,14,16,20,26,30,34,40,50,60,64
Contact spacing	2,54 mm x 2,54 mm
Test voltage Ur.m.s	1 kV
Working voltage	500 V for pollution degree 1
Working current acc. to IEC 60512-2	See derating diagram
Contact resistance	max. 20mOhm
Insulation resistance	min. 10 ⁹ Ohm
Temperature range	-55°C ... +125°C (solder) -55°C ... +105°C (press-in)
Termination technology	solder, press-in
Clearance & creepage distance	min. 0,5 mm clearance min. 0,56 creepage

Insertion and withdrawal forces	6-pole max. 12N for PL1-2 / 18N for PL3	; 30-pole max. 60N for PL1-2 / 90N for PL3	
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Mating cycles	S4 surface treatment	Au over PdNi (min. 0,76 µm)	
	PL 1 acc. to IEC 60603-13	500 mating cycles	10 days gas test
	PL 2 acc. to IEC 60603-13	250 mating cycles	4 days gas test
	PL 3 acc. to IEC 60603-13	50 mating cycles	No gas test

UL file	E 102079
RoHS - compliant	Yes
Leadfree	Yes
Hot plugging	No

Insulator material

Material	PBT (thermoplastics, glass fiber reinforcement 30%)
Color	black (RAL 7001) or grey (RAL 7032) for solder grey (RAL 7053) for press-in
UL classification	UL94-V0
Material group acc. IEC 60664-1	IIIa (175 < CTI < 400)
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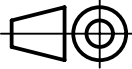
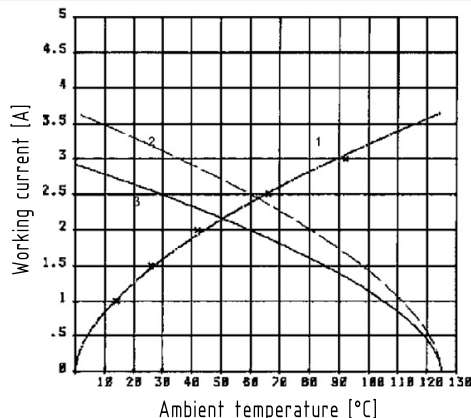
Contact material

Contact material	Copper alloy
Plating termination zone	Sn over Ni for solder, Ni for press-in
Plating contact sliding side	Au or Au over PdNi (according to performance level)

Derating diagram acc to IEC 60512-2 (Current carrying capacity)

The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals. The current capacity-curve is valid for continuous, not interrupted current-loaded contacts of connectors when simultaneous power on all contacts is given without exceeding the maximum temperature. Control and test procedures according to DIN IEC 60512.

- 1) Temperature rise
- 2) Derating
- 3) Derating curve at I max x 0.8(IEC 60512-2)



All Dimensions in mm
Original Size DIN A3

Scale
1:1

Free size tol.

Ref.
Sub. DS 09181100001 / 500000101780 / 2016-07-25



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Created by
STORCK

Inspected by
LEHNERT

Standardisation
HOFFMANN

Date
2016-09-05

State
Final Release

Title
SEK 18 male low profile solder and press-in

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100554984/UGD/001/F
500000107692

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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
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- Экспресс доставка в любую точку России;
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- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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